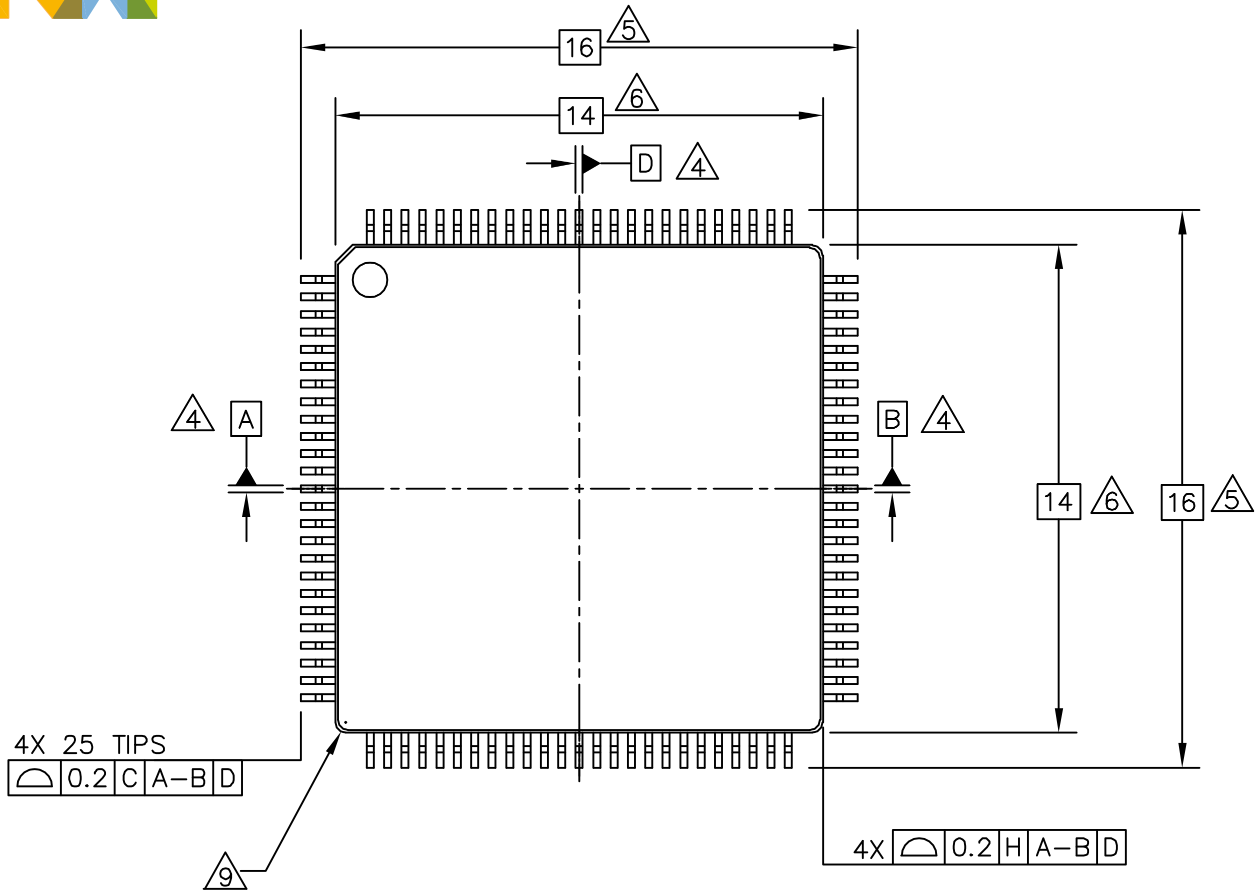

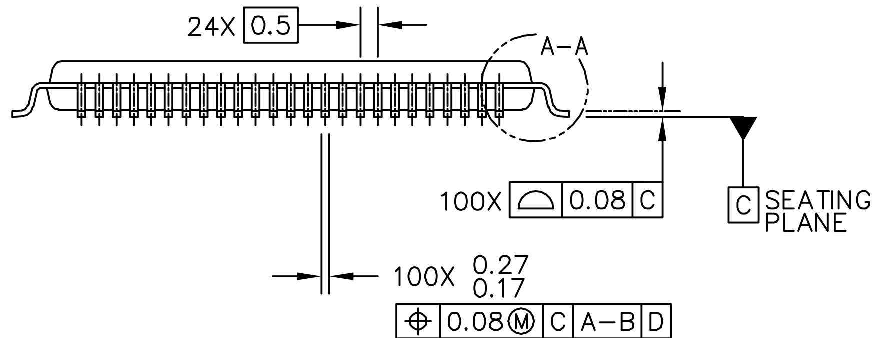

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	STANDARD: JEDEC MS–026 BED	
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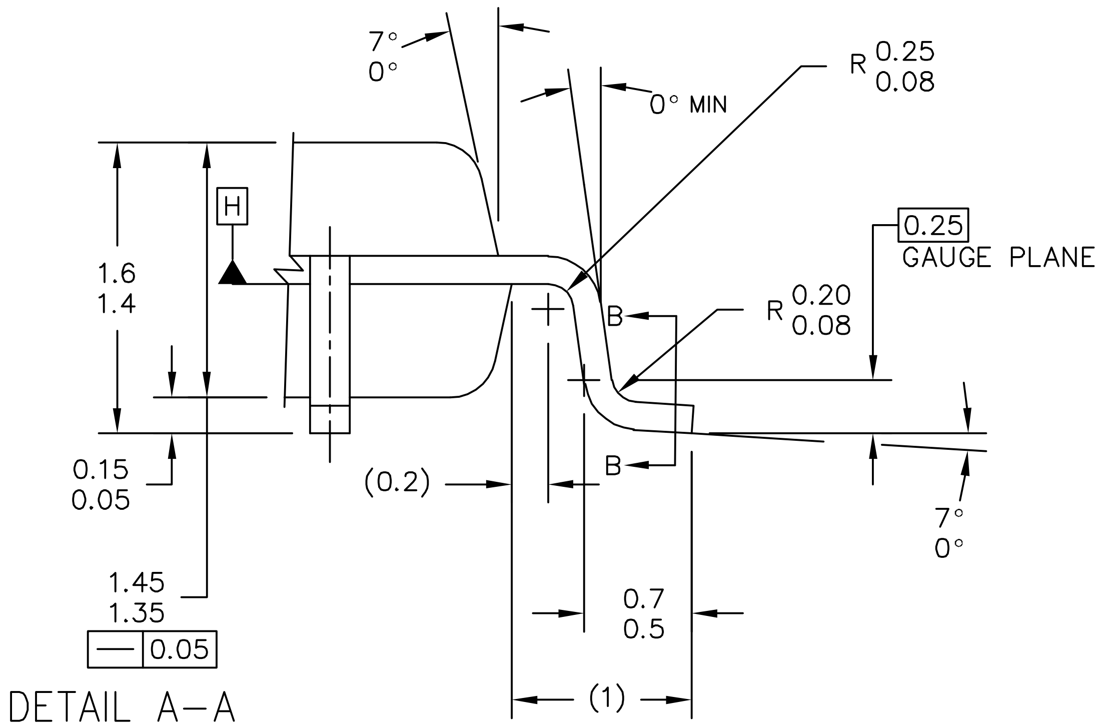
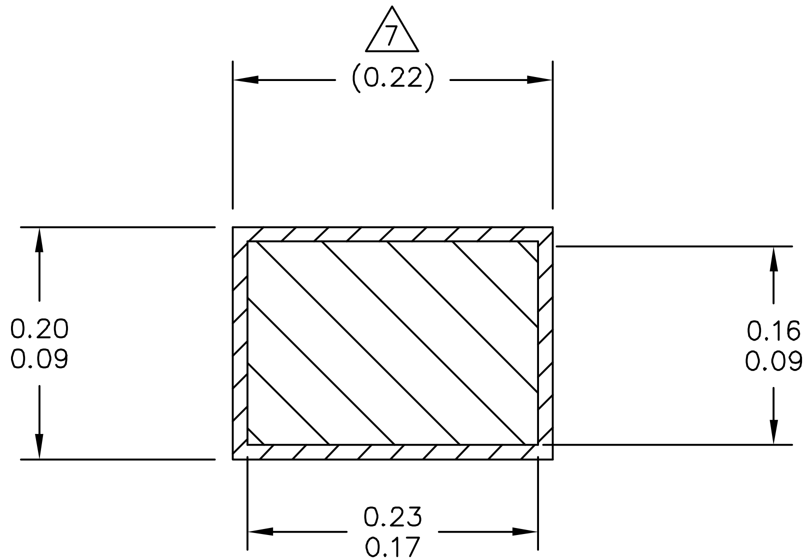


DETAIL A–A



SECTION B–B

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1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.

2. CONTROLLING DIMENSION: MILLIMETER

3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

△4. DATUMS A, B, AND D TO BE DETERMINED AT DATUM PLANE H.

△5. DIMENSIONS TO BE DETERIMINED AT SEATING PLANE, DATUM C.

△6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

△7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD IS 0.07.

8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.

△9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

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